

**SECTION I**  
**LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY**

<b>MANUFACTURER INFORMATION:</b> <b>Firan Technology Group</b> 250 Finchdene Square, Scarborough, M1X 1A5, Ontario, Canada	<b>PLANT LOCATION:</b> Same Address as Manufacturer	<b>CAGE Code:</b> L2665 <b>Phone:</b> 416-299-4000 <b>Fax:</b> 416-292-4308 <b>E-Mail:</b> info@ftgcorp.com
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**CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION**

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2  
 Qualification Letters: VQE-05-009339, VQE-06-010764, VQE-06-010889, VQE-15-028987, VQE-16-030295, VQE-17-031083, VQE-17-031084  
 Rigid Base Material: BI: Aramid Fabric, Nonwoven, Polyimide Resin  
 Max. Panel Size: 18" x 24"  
 Max. Number of Layers: 14  
 Max. Board Thickness: .106"  
 Min. Hole Size: .02" Drilled Plated-Through Hole Before Plating  
 Aspect Ratio: 5.1:1 Through-Hole  
 Min. Conductor Width/Space: .004"/.004"  
 Hole Preparation: Permanganate Desmear, Plasma Etchback  
 Hole Wall Conductive Coating: Electroless Copper  
 Copper Plating: Direct Current Plate, Pulse Plate  
 Solder Resist: Dry Film, Liquid Photoimageable  
 Finish System: ENIG, HASL, Hot Oil Reflow of Plated Sn/Pb, ImmAg  
 Additional Fab Capabilities: Foil Lamination  
 Controlled Impedance: Differential, Single-Ended

**CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION**

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2  
 Qualification Letters: VQE-05-009339, VQE-06-010764, VQE-06-010889, VQE-15-028987, VQE-16-030295, VQE-17-031083  
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant  
 Max. Panel Size: 18" x 24"  
 Max. Number of Layers: 30  
 Max. Board Thickness: .245"  
 Min. Hole Size: .005" Laser Ablated Plated Hole Size Before Plating, .008" Drilled Plated-Through Hole Before Plating  
 Aspect Ratio: 1.01:1 Microvia, 15.9:1 Through-Hole  
 Min. Conductor Width/Space: .004"/.003"  
 Hole Preparation: Permanganate Desmear, Plasma Etchback  
 Hole Wall Conductive Coating: Electroless Copper  
 Copper Plating: Direct Current Plate, Pulse Plate  
 Hole Fill/Via Plug: Non-Conductive  
 Solder Resist: Dry Film, Liquid Photoimageable  
 Finish System: ENIG, HASL, Hot Oil Reflow of Plated Sn/Pb, ImmAg  
 Additional Fab Capabilities: Blind Vias, Buried Vias, Foil Lamination, Sequential Lamination  
 Controlled Impedance: Differential, Single-Ended

**CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION**

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2  
 Qualification Letters: VQE-05-009339, VQE-06-010764, VQE-06-010889, VQE-15-028987, VQE-16-030295, VQE-17-031083  
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant  
 Max. Panel Size: 21" x 24"  
 Max. Number of Layers: 20  
 Max. Board Thickness: .17"  
 Min. Hole Size: .0059" Laser Ablated Plated Hole Size Before Plating, .01" Drilled Plated-Through Hole Before Plating  
 Aspect Ratio: 0.6:1 Microvia, 9.6:1 Through-Hole  
 Min. Conductor Width/Space: .0035"/.003"  
 Hole Preparation: Permanganate Desmear, Plasma Etchback  
 Hole Wall Conductive Coating: Electroless Copper  
 Copper Plating: Direct Current Plate, Pulse Plate  
 Hole Fill/Via Plug: Non-Conductive  
 Solder Resist: Dry Film, Liquid Photoimageable  
 Finish System: ENIG, HASL, Hot Oil Reflow of Plated Sn/Pb, ImmAg  
 Additional Fab Capabilities: Blind Vias, Foil Lamination, Sequential Lamination  
 Controlled Impedance: Differential, Single-Ended

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Specification: MIL-PRF-31032/1, MIL-PRF-31032/2  
 Qualification Letters: VQE-05-009339, VQE-06-010764, VQE-06-010889, VQE-15-028987, VQE-16-030295, VQE-17-031083  
 Rigid Base Material: GM: Glass Base, Woven, Triazine and/or Bismaleimide Modified Epoxy Resin, Flame Resistant  
 Max. Panel Size: 21" x 24"  
 Max. Number of Layers: 24  
 Max. Board Thickness: .137"  
 Min. Hole Size: .01" Drilled Plated-Through Hole Before Plating  
 Aspect Ratio: 9.3:1 Through-Hole  
 Min. Conductor Width/Space: .004"/.0037"  
 Hole Preparation: Permanganate Desmear, Plasma Etchback  
 Hole Wall Conductive Coating: Electroless Copper  
 Copper Plating: Direct Current Plate, Pulse Plate  
 Hole Fill/Via Plug: Non-Conductive  
 Solder Resist: Dry Film, Liquid Photoimageable  
 Finish System: ENIG, HASL, Hot Oil Reflow of Plated Sn/Pb, ImmAg  
 Additional Fab Capabilities: Blind Vias, Foil Lamination, Sequential Lamination

**CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION**

Specification: MIL-PRF-31032/3, MIL-PRF-31032/4  
 Qualification Letters: VQE-15-029018, VQE-16-030295  
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant  
 Flex Base Material: Copper Clad Adhesiveless Polyimide  
 Max. Panel Size: 12" x 18"  
 Max. Number of Layers: 12  
 Max. Board Thickness: .086"  
 Min. Hole Size: .008" Drilled Plated-Through Hole Before Plating  
 Aspect Ratio: 10:1  
 Min. Conductor Width/Space: .004"/.004"  
 Hole Preparation: Plasma Desmear  
 Hole Wall Conductive Coating: Electroless Copper  
 Copper Plating: Direct Current Plate, Pulse Plate  
 Solder Resist: Liquid Photoimageable  
 Finish System: ENIG, HASL, Hot Oil Reflow of Plated Sn/Pb, ImmAg  
 Flex Usage: Use A (Flex During Installation)